



ADS5120

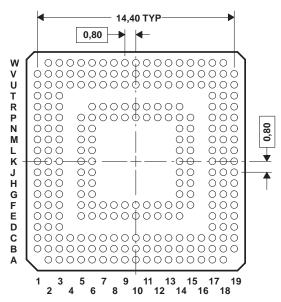
SBAS247 - MARCH 2002

8-Channel, 10-Bit, 40MSPS, 1.8V CMOS ANALOG-TO-DIGITAL CONVERTER

FEATURES

- 8 DIFFERENTIAL ANALOG INPUTS
- 1Vp-p DIFFERENTIAL INPUT RANGE
- INT./EXT. VOLTAGE REFERENCE
- ANALOG/DIGITAL SUPPLY 1.8V
- DIGITAL I/O SUPPLY 1.8V/3.3V
- INTEGRAL NONLINEARITY: ±0.8LSB
- SIGNAL-TO-NOISE: 57dB at f_{IN} = 20MHz
- SPURIOUS-FREE DYNAMIC RANGE: 65dB at f_{IN} = 20MHz
- 794mW POWER DISSIPATION
- INDIVIDUAL CHANNEL POWER-DOWN
- 257-LEAD, 0.8 BALL PITCH, PLASTIC MicroSTAR BGA™ (16 • 16mm)

MicroSTAR BGA is a trademark of Texas Instruments.



DESCRIPTION

The ADS5120 is a low-power, 8-channel, 10-bit, 40MSPS CMOS Analog-to-Digital Converter (ADC) that operates from a single 1.8V supply, while offering 1.8V and 3.3V digital I/O flexibility. A single-ended input clock is used for simultaneous sampling of up to eight analog differential input channels. The flexible duty cycle adjust circuit (DCASEL) allows the use of a non-50% clock duty cycle. Individual standby pins allow users the ability to power-down any number of ADCs. A sample-and-hold stage is added in front of the ADC and a digital error correction circuit is used to generate the final digital code.

The internal reference can be bypassed to use an external reference to suit the accuracy and temperature drift requirements of the application. A 10-bit parallel bus on eight channels is provided with 3-state outputs.

The speed, resolution, and low-power of the ADS5120 makes it ideal for applications requiring high-density signal processing in low-power environments.

The ADS5120 is characterized for operation from 0°C to 70°C.

AVAILABLE OPTIONS

T _A	PACKAGED DEVICES MICROSTAR BGA-257
0°C to 70°C	ADS5120CGHK



This device has ESD-CDM sensitivity and special handling precautions should be taken.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



ABSOLUTE MAXIMUM RATINGS(1)

Supply Voltage: AV _{DD} to AGND, DV _{DD} to DGND0.3V to +2.2V
DRV _{DD} to DRGND –0.3V to +4.0\
AGND to DGND0.3V to +0.3V
AV _{DD} to DV _{DD} 2.2V to +2.2V
Reference Voltage Input Range REFT, REFB to AGND0.3V to AV _{DD} + 0.3V
Analog Input Voltage Range AIN to AGND0.3V to AV _{DD} + 0.3V
Clock Input CLK to DGND0.3V to AV _{DD} + 0.3V
Digital Input to DGND0.3V to DV _{DD} + 0.3V
Digital Outputs to DRGND0.3V to DRV _{DD} + 0.3V
ESD CDM 400\
Operating Temperature Range (T _J)0°C to +105°C
Storage Temperature Range (T _{STG})65°C + 150°C

NOTE: (1) Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods may affect device reliability.

PACKAGE/ORDERING INFORMATION



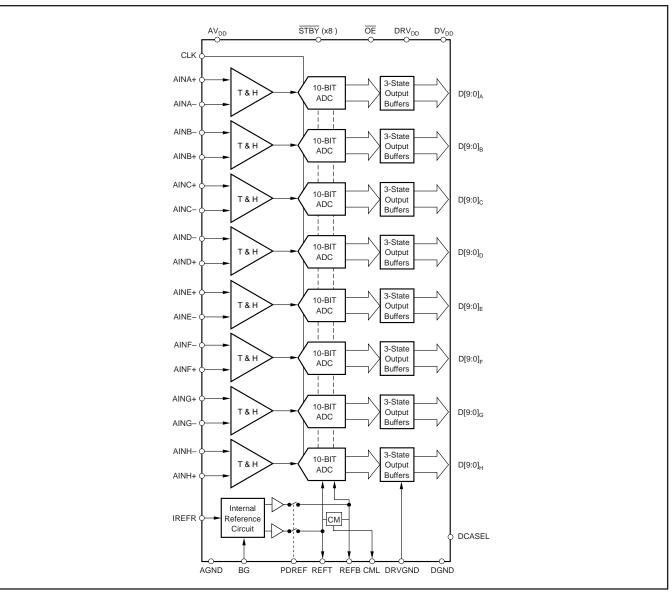
This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR ⁽¹⁾	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
ADS5120	MicroSTAR BGA-257	GHK	0°C to +70°C	ADS5120CGHK	ADS5120CGHK	Tray, 90

NOTE: (1) For the most current specifications and package information, refer to our web site at www.ti.com.

BLOCK DIAGRAM





DC CHARACTERISTICS

 $AV_{DD} = DV_{DD} = 1.8V$, $DRV_{DD} = 3.3V$, Clock = 40MSPS, 50% Clock Duty Cycle, -0.5dBFS Input Span, Internal Reference, $T_{MIN} = 0^{\circ}C$, and $T_{MAX} = +70^{\circ}C$, unless otherwise noted.

			ADS5120		
PARAMETER	CONDITION	MIN	TYP	MAX	UNITS
RESOLUTION			10		Bits
DC ACCURACY Differential Nonlinearity (DNL) Integral Nonlinearity (INL) No Missing Codes		-0.9 -1.5	±0.4 ±0.8 Tested	+1.0 +1.5	LSB LSB
Gain Error Offset Error Gain Temperature Coefficient Gain Matching	External Reference External Reference	-1.0	0.1 0.2 80 ±0.4	+1.0 +1.8	%FSR %FSR ppm/°C %FSR
ANALOG INPUT Input Voltage Range (AIN+, AIN–) Input Voltage, Differential Full-Scale Input Common-Mode Range Input Resistance, R _{IN} Input Capacitance, C _{IN}	f _{CLK} = 40MSPS	REFB (I	1 REFT + REFB) 83 5	REFT /2	V Vp-p V kΩ pF
INTERNAL REFERENCE VOLTAGES Reference, Top (REFT) Reference, Bottom (REFB) Int. Reference Temperature Coefficient		1.30 0.76	1.34 0.81 50	1.40 0.85	V V ppm/°C
EXTERNAL REFERENCE GENERATION Reference, Top (REFT) Reference, Bottom (REFB) Input Resistance, REFR _{IN} (between REFB and REFT)		1.15 0.65	1.25 0.75 80	1.35 0.85	V V Ω
POWER SUPPLY Operating Supply Current, I _{DD} Analog Operating Supply Current, IAV _{DD} Digital Operating Supply Current, IDV _{DD} Driver Operating Supply Current, IDRV _{DD} Operating Voltage	$f_{IN} = 3.5MHz$ $C_L = 20pF$		398 294 44 53	450 340 49 60	mA mA mA mA
AV _{DD} DV _{DD} DRV _{DD} Power-Dissipation, PD Standby Power (STBY), PD, all ADCs PSRR, Power-Supply Rejection Ratio	CLK Running ±5%	1.65 1.65 1.65	1.8 1.8 1.8 794 7 0.8	2.0 2.0 3.6 850	V V mW mW mV/V

DC CHARACTERISTICS

AV_{DD} = DV_{DD} = 1.8V, DRV_{DD} = 3.3V, Clock = 40MSPS, 50% Clock Duty Cycle, -0.5dBFS Input Span, Internal Reference, T_{MIN} to T_{MAX}, unless otherwise noted.

			ADS5120		
PARAMETER	CONDITION	MIN	TYP	MAX	UNITS
DIGITAL INPUTS (STBY A-H, PDREF, OE) High-Level Input Voltage, (V _{IH}) Low-Level Input Voltage, (V _{IL}) High-Level Input Current, I _{IH} Low-Level Input Current, I _{IL}	$\label{eq:DRV_DD} \begin{split} DRV_{DD} &= 3.3V/1.8V \\ V_{IH} &= DRV_{DD} \\ V_{IL} &= 0V \end{split}$	0.70 • DRV _{DD}		0.25 • DRV _{DD} ±1 ±1	V V μΑ μΑ
DIGITAL INPUTS (DCASEL) High-Level Input Voltage, V _{IH} Low-Level Input Voltage, V _{IL} High-Level Input Current, I _{IH} Low-Level Input Current, I _{IL}	$V_{IH} = DV_{DD}$ $V_{IL} = 0V$	0.70 • DV _{DD}		0.25 • DV _{DD} ±1 ±1	V V μΑ μΑ
DIGITAL OUTPUTS (DRV_{DD} = 3.3/1.8V) High-Level Output Voltage (V _{OH}) Low-Level Output Voltage (V _{OL}) External Load Capacitance, C _L Three-State Leakage Current, I _{LEAK}	$I_{OH} = -50\mu A$ $I_{OL} = 50\mu A$ $\overline{OE} = HIGH$	0.8 • DRV _{DD}	15	0.2 • DRV _{DD} ±1	V V pF μA



TARGETED AC CHARACTERISTICS

 $AV_{DD} = DV_{DD} = 1.8V$, $DRV_{DD} = 3.3V$, 50% Clock Duty Cycle, CLK = 40MSPS, Analog input at -0.5dBFS Input Span, Internal voltage reference, $T_{MIN} = 0^{\circ}C$, $T_{MAX} = 70^{\circ}C$, typical values are at $T_A = 25^{\circ}C$, unless otherwise noted.

PARAMETER		CONDITION	MIN	TYP	MAX	UNITS
Signal-to-Noise Ratio	(SNR)	$f_{IN} = 3.5MHz$	55	58		dB
		f _{IN} = 10MHz	55	58		dB
		$f_{IN} = 20MHz$		58		dB
Signal-to-Noise and Distortion	(SINAD)	f _{IN} = 3.5MHz	55	57		dB
		f _{IN} = 10MHz	55	57		dB
		$f_{IN} = 20MHz$		57		dB
Effective Number of Bits	(ENOB)	f _{IN} = 3.5MHz	8.8	9.2		Bits
		$f_{IN} = 10MHz$	8.8	9.2		Bits
		$f_{IN} = 20MHz$	8.8	9.2		Bits
Spurious-Free Dynamic Range	(SFDR)	f _{IN} = 3.5MHz	65	73		dBc
		$f_{IN} = 10MHz$	65	72		dBc
		$f_{IN} = 20MHz$		72		dBc
2nd-Harmonic Distortion	(HD2)	f _{IN} = 3.5MHz	68	79		dBc
		$f_{IN} = 10MHz$	68	80		dBc
		$f_{IN} = 20MHz$		80		dBc
3rd-Harmonic Distortion	(HD3)	f _{IN} = 3.5MHz	65	76		dBc
		$f_{IN} = 10MHz$	65	78		dBc
		$f_{IN} = 20MHz$		73		dBc
2-Tone Intermod. Distortion	(IMD)	$f_1 = 4.43MHz$, $f_2 = 4.53MHz$ at -6.5dB		-69		dBFS
Channel-to-Channel Crosstalk		$f_{IN} = 10MHz, DRV_{DD} = 3.3V$		89		dB
Large-Signal Bandwidth	(FPBW)			300		MHz
Overvoltage Recovery Time ⁽¹⁾				20		ns
Differential Gain ⁽¹⁾				±1		%
Differential Phase ⁽¹⁾				±0.25		Degree

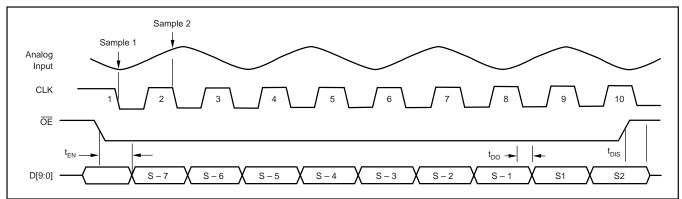
NOTE: (1) Assured by design.

SWITCHING CHARACTERISTICS

 $AV_{DD} = DV_{DD} = 1.8V$, $DRV_{DD} = 3.3V$, 50% Clock Duty Cycle, CLK = 40MSPS, Analog input at -0.5dBFS Input Span, Internal voltage reference, $T_{MIN} = 0^{\circ}C$, $T_{MAX} = 70^{\circ}C$, Typical values are at $T_A = 25^{\circ}C$.

			ADS5120		
PARAMETER	CONDITION	MIN	TYP	MAX	UNITS
$\begin{array}{c c} \mbox{Maximum Conversion Rate} \\ \mbox{Clock Duty Cycle} \\ \mbox{Data Latency}^{(1)} \\ \mbox{Clock} \downarrow \mbox{to Data Valid} & t_{\mbox{DO}}^{(1)} \\ \hline \mbox{OE} \downarrow \mbox{to Outputs Enabled} & t_{\mbox{EN}}^{(1)} \\ \hline \mbox{OE} \uparrow \mbox{Rising to Outputs Tri-Stated} & t_{\mbox{DIS}} \\ \mbox{Aperture Delay} \\ \mbox{Aperture Uncertainty (Jitter)} \end{array}$		1	30 to 70 7 8 8 8 1 2	40 10	MSPS % Clk Cycles ns ns ns ps, rms

TIMING DIAGRAM (Per ADC Channel)







PIN DESCRIPTIONS

NAME	PINS	I/O	TERMINAL DESCRIPTION
AV _{DD}	C6, C7, E6, F1, F3, F5, F6, J6, N3, P3, P5, P6, P7, R6, V6, W6	I	Analog Supply, (1.8V)
AGND	A3, A5, B5, B9, C1, C5, C9, E3, E7, F7, G1, G5, G6, H6, J1, J2, M2, N5, N6, P8,	1	Analog Ground
	R1, R2, R3, R7, U1, U5, U10, V5, V10, W3, W7		
AINA+	U7	1	Analog Input Channel A
AINA-	V7	1	Complementary Analog Input Channel A
AINB+	W4	1	Analog Input Channel B
AINB-	V4	1	Complementary Analog Input Channel B
AINC+	T1	1	Analog Input Channel C
AINC-	Τ2		Complementary Analog Input Channel C
AIND+	P2		Analog Input Channel D
AIND-	P1		Complementary Analog Input Channel D
AINE+	G3		Analog Input Channel E
AINE-	G2		Complementary Analog Input Channel E
AINF+	D1		Analog Input Channel F
AINF-	D2		Complementary Analog Input Channel F
AING+	A4		Analog Input Channel G
AING-	B4		Complementary Analog Input Channel G
AINH+	B6	'	Analog Input Channel H
AINH-	A6		Complementary Analog Input Channel H
CLK	W9		Clock Input
REFT		1/0	Reference Top
REFB	K3, L1, J3	1/0 1/0	Reference Bottom
CML	K5, J5, L5	0	
	L2, L3		Common-Mode Level Output
BG	К1	I/O	Bandgap Decoupling (Decouple with 1µF cap to AGND and 100k Ω to AV _{DD})
IREFR	K6	1	Internal Reference Bias Current (Connect 6.19 Ω resistor from this pin AGND to set internal bias amplifier current.)
DNC	L6	1	Do Not Connect
DNC	M1	1	Do Not Connect
NC	E1, E2, K2, U6, W5		No Internal Connection
DCASEL	N2		Duty Cycle Adjust
DV_{DD}	C2, C3, C4, D3, E8, F8, H3, H5, M3, M5, R8, T3, U3, U3, U4, U8, V3, P13, R13	1	Digital Supply (1.8V)
	P17, L15, J14, F17, F12, E12		
DGND	A2, A7, B1, B2, B3, B7, B13, C13, G15, H1, H2, H17, L17, M6, N1, N15, U2, U13,	1	Digital Ground
	U14, V1, V2, V8, W2, W8		
PDREF	V9	I	Power-Down Ref: 0 = internal reference, 1 = external reference. In external reference mode connect REFT to BG pin.
STBY A	W10	Т	Power-Down Channel A
STBY B	P9		Power-Down Channel B
STBY C	R9	1	Power-Down Channel C
STBY D	U9	1	Power-Down Channel D
STBY E	C8		Power-Down Channel E
STBY F	B8		Power-Down Channel F
STBY G	 A8		Power-Down Channel G
STBY H	A9		Power-Down Channel H
OE	P10	1	Enable all Digital Outputs, Ch. A-H. \overline{OE} : 0 = Outputs Enable. \overline{OE} : 1 = Outputs disabled (3-State).
	B17, C16, D17, E9, E10, E11, E17, F9, H14, H15, K17, L14, N14, P12, P14, P15	I	Driver Digital Supply (1.8V or 3.3V)
	R10, R12, R14	'	
DRGND	E13, F10, F11, F13, F14, F15, G14, G17, M14, M15, M17, N17, U11, U12, U15, U16	1	Driver Digital Ground



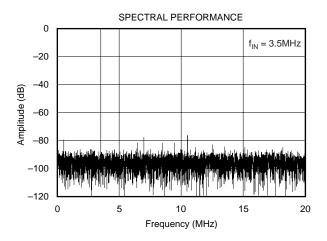
DATA OUTPUT PINS

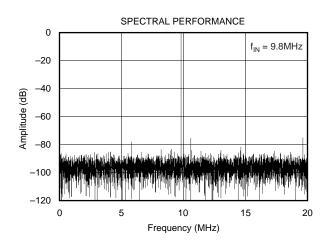
NAME	PINS	I/O	TERMINAL DESCRIPTION	NAME	PINS	I/O	TERMINAL DESCRIPTION
D0A	V14	0	Bit 1, Channel A (LSB)	D0E	F18	0	Bit 1, Channel E (LSB)
D1A	W14	Õ	Bit 2, Channel A	D1E	F19	0	Bit 2, Channel E
D2A	V13	0	Bit 3, Channel A	D2E	G18	0	Bit 3, Channel E
D3A	W13	0	Bit 4, Channel A	D3E	G19	0	Bit 4, Channel E
D4A	V12	0	Bit 5, Channel A	D4E	H18	0	Bit 5, Channel E
D5A	W12	0	Bit 6, Channel A	D5E	H19	0	Bit 6, Channel E
D6A	R11	0	Bit 7, Channel A	D6E	J15	0	Bit 7, Channel E
D7A	P11	0	Bit 8, Channel A	D7E	J17	0	Bit 8, Channel E
D8A	V11	0	Bit 9, Channel A	D8E	J18	0	Bit 9, Channel E
D9A	W11	0	Bit 10, Channel A (MSB)	D9E	J19	0	Bit 10, Channel E (MSB)
D0B	V19	0	Bit 1, Channel B (LSB)	D0F	A18	0	Bit 1, Channel F (LSB)
D1B	V18	0	Bit 2, Channel B	D1F	B18	0	Bit 2, Channel F
D2B	U17	0	Bit 3, Channel B	D2F	C17	0	Bit 3, Channel F
D3B	W18	0	Bit 4, Channel B	D3F	B19	0	Bit 4, Channel F
D4B	V17	0	Bit 5, Channel B	D4F	C18	0	Bit 5, Channel F
D5B	W17	0	Bit 6, Channel B	D5F	C19	0	Bit 6, Channel F
D6B	V16	0	Bit 7, Channel B	D6F	D18	0	Bit 7, Channel F
D7B	W16	0	Bit 8, Channel B	D7F	D19	0	Bit 8, Channel F
D8B	V15	0	Bit 9, Channel B	D8F	E18	0	Bit 9, Channel F
D9B	W15	0	Bit 10, Channel B (MSB)	D9F	E19	0	Bit 10, Channel F (MSB)
DOC	P19	0	Bit 1, Channel C (LSB)	D0G	A14	0	Bit 1, Channel G (LSB)
D1C	P18	0	Bit 2, Channel C	D1G	B14	0	Bit 2, Channel G
D2C	R19	0	Bit 3, Channel C	D2G	C14	0	Bit 3, Channel G
D3C	R18	0	Bit 4, Channel C	D3G	A15	0	Bit 4, Channel G
D4C	R17	0	Bit 5, Channel C	D4G	B15	0	Bit 5, Channel G
D5C	R19	0	Bit 6, Channel C	D5G	E14	0	Bit 6, Channel G
D6C	T18	0	Bit 7, Channel C	D6G	C15	0	Bit 7, Channel G
D7C	U19	0	Bit 8, Channel C	D7G	A16	0	Bit 8, Channel G
D8C	U18	0	Bit 9, Channel C	D8G	B16	0	Bit 9, Channel G
D9C	T17	0	Bit 10, Channel C (MSB)	D9G	A17	0	Bit 10, Channel G (MSB)
D0D	K14	0	Bit 1, Channel D (LSB)	D0H	C10	0	Bit 1, Channel H (LSB)
D1D	K15	0	Bit 2, Channel D	D1H	B10	0	Bit 2, Channel H
D2D	K18	0	Bit 3, Channel D	D2H	A10	0	Bit 3, Channel H
D3D	K19	0	Bit 4, Channel D	D3H	C11	0	Bit 4, Channel H
D4D	L18	0	Bit 5, Channel D	D4H	B11	0	Bit 5, Channel H
D5D	L19	0	Bit 6, Channel D	D5H	A11	0	Bit 6, Channel H
D6D	M19	0	Bit 7, Channel D	D6H	A12	0	Bit 7, Channel H
D7D	M18	0	Bit 8, Channel D	D7H	B12	0	Bit 8, Channel H
D8D	N19	0	Bit 9, Channel D	D8H	C12	0	Bit 9, Channel H
D9D	N18	0	Bit 10, Channel D (MSB)	D9H	A13	0	Bit 10, Channel H (MSB)

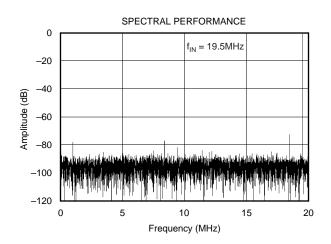


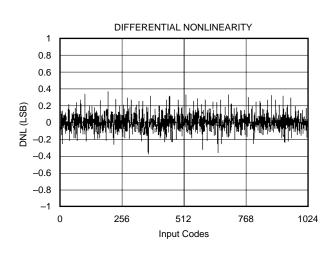
TYPICAL CHARACTERISTICS

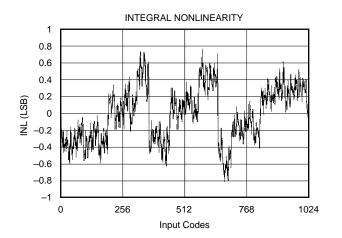
 $T_{A} = 25^{\circ}C, \ AV_{DD} = DV_{DD} = 1.8V, \ DRV_{DD} = 3.3V, \ f_{IN} = -0.5dBFS, \ Internal \ Reference, \ Clock = 40MSPS, \ Differential \ Input \ Range = 1Vp-p, \ unless \ otherwise \ noted.$



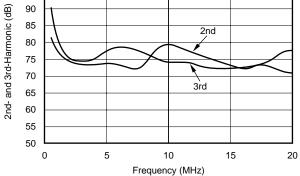








2ND- AND 3RD-HARMONIC vs INPUT FREQUENCY





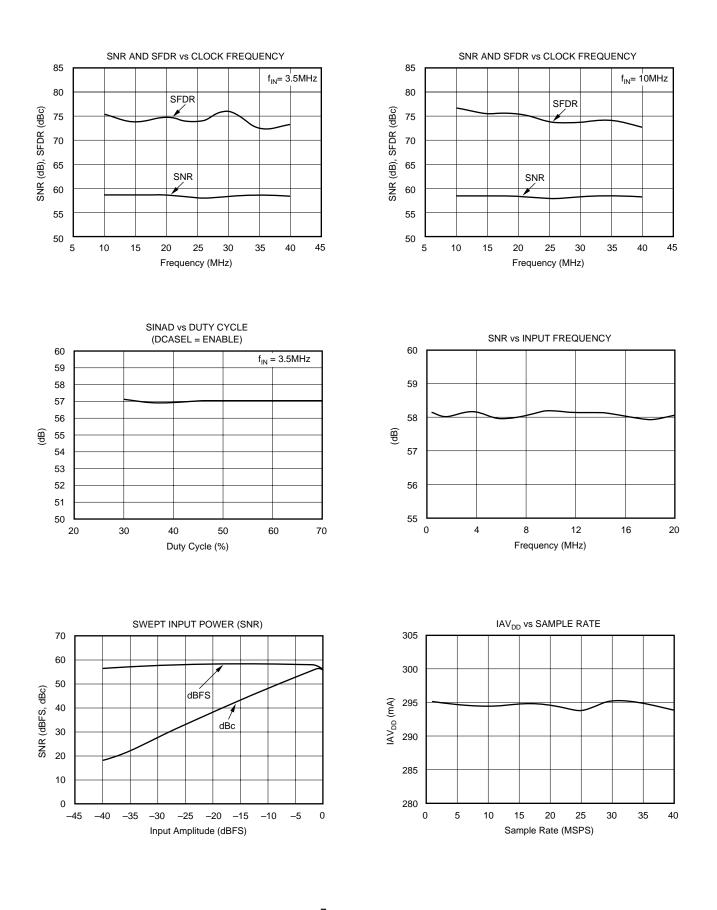


100

95

TYPICAL CHARACTERISTICS (Cont.)

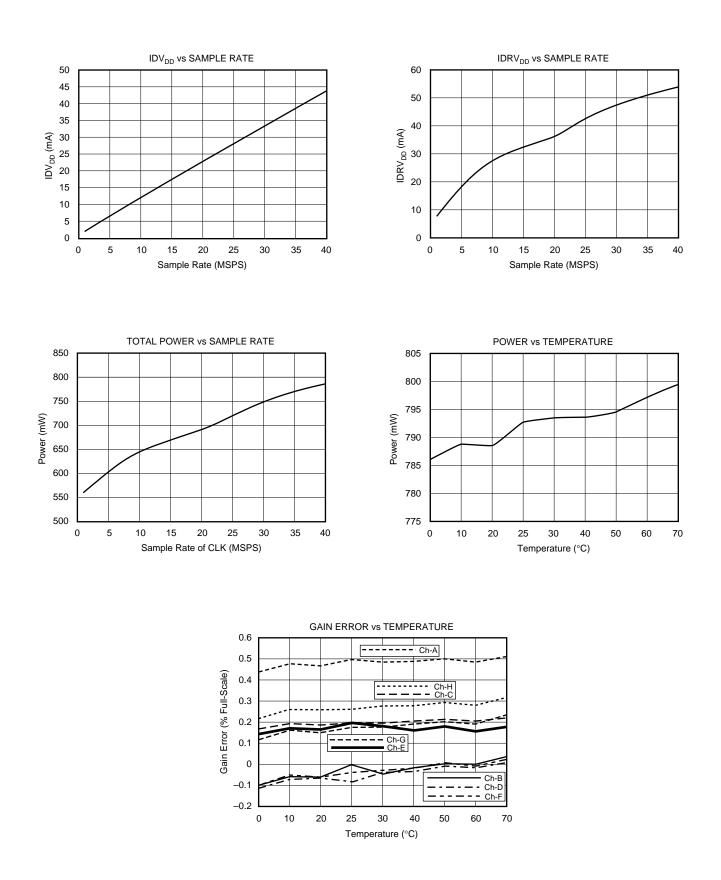
T_A = 25°C, AV_{DD} = DV_{DD} = 1.8V, DRV_{DD} = 3.3V, f_{IN} = -0.5dBFS, Internal Reference, Clock = 40MSPS, Differential Input Range = 1Vp-p, unless otherwise noted.





TYPICAL CHARACTERISTICS (Cont.)

 $T_{A} = 25^{\circ}C, \ AV_{DD} = DV_{DD} = 1.8V, \ DRV_{DD} = 3.3V, \ f_{IN} = -0.5dBFS, \ Internal \ Reference, \ Clock = 40MSPS, \ Differential \ Input \ Range = 1Vp-p, \ unless \ otherwise \ noted.$







APPLICATION INFORMATION

CONVERTER OPERATION

The ADS5120 is an 8-channel, simultaneous sampling ADC. Its low power (100mW/channel) and high sampling rate of 40MSPS is achieved using a state-of-the-art switched capacitor pipeline architecture built on an advanced low-voltage CMOS process. The ADS5120 primarily operates from a +1.8V single supply. For additional interfacing flexibility, the digital I/O supply (DRV_{DD}) can be set to either +1.8V or +3.3V. The ADC core of each channel consists of 10 pipeline stages. Each of the 10 stages produces one digital bit per stage. Both the rising and the falling clock edges are utilized to propagate the sample through the pipeline every half clock, for a total of five clock cycles. Two additional clock cycles are needed to pass the sample data through the digital error correction logic and the output latches. The total pipeline delay, or data latency, is therefore seven clock cycles long. Since a common clock controls the timing of all eight channels, the analog signal is sampled at the same time, as well as the data on the parallel ports which becomes updated simultaneously.

ANALOG INPUTS

The analog input for each channel of the ADS5120 consists of a differential track-and-hold amplifier implemented using a switched capacitor technique, shown in Figure 1. This differential input topology along with closely matched capacitors produces a high level of AC-performance up to high sampling rates.

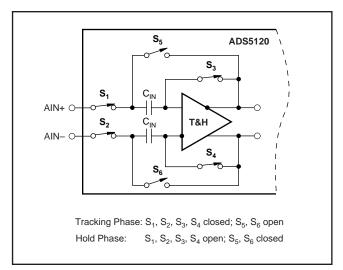


FIGURE 1. Simplified Circuit of Input Track-and-Hold.

INPUT IMPEDANCE

Because of the switched capacitor input track-and-hold amplifier, the input impedance of the ADS5120 is effectively capacitive, and the driving source needs to provide sufficient slew current to charge and discharge the input sampling capacitor while the track-and-hold amplifier is in track mode. The input impedance of the ADS5120 is also a function of the sampling rate. As the sampling frequency increases, the input impedance decreases linearly at a rate of 1/fs. For most applications, this does not represent a limitation since the impedance remains relatively high, for example, approximately $83k\Omega$ at the max sampling rate of 40MSPS. For applications using an op amp to drive the ADC, it is recommended that a series resistor, typically 10Ω to 50Ω , be added between the amplifier's output and the converter inputs. This will isolate the converter's capacitive input from the driver and avoid potential gain peaking, or instability.

INPUT BIASING

The ADS5120 operates from a single +1.8V analog supply, and requires each of the analog inputs (AIN+, AIN–) to be externally biased by a suitable common-mode voltage. For example, with a common-mode voltage of +1V, the 1Vp-p full-scale, differential input signal will swing symmetrically around +1V, or between 0.75V and 1.25V. This is determined by the two reference voltages, the top-reference (REFT), and the bottom reference (REFB). Typically, the input common-mode level is related to the reference voltages and defined as (REFT + REFB)/2. This reference mid-point is provided at the CML-pin and can directly be used for input biasing purposes. The voltage at CML will assume the mid-point for either internal or external reference operation. In any case, it is recommended to bypass the CML pin with a ceramic 0.1 μ F capacitor.

DRIVING THE ANALOG INPUTS

Differential versus Single-Ended

The analog input of the ADS5120 allows it to be driven either single-ended or differentially. Differential operation of the ADS5120 requires an input signal that consists of an inphase and a 180° out-of-phase part simultaneously applied to the inputs (AIN+, AIN–). The differential operation offers a number of advantages, which in most applications will be instrumental in achieving the best dynamic performance of the ADS5120:

- The signal swing is half of that required for the singleended operation and is therefore less demanding to achieve while maintaining good linearity performance from the signal source.
- The reduced signal swing allows for more headroom of the interface circuitry and therefore a wider selection of the best suitable driver op amp.
- Even-order harmonics are minimized.
- Improves the noise immunity based on the converter's common-mode input rejection.



For the single-ended mode, the signal is applied to one of the inputs while the other input is biased with a DC voltage to the required common-mode level. Both inputs are identical in terms of their impedance and performance. Applying the signal to the complementary input (AIN–) instead of the AIN+ input, however, will invert the orientation of the input signal relative to the output code. This could be helpful, for example, if the input driver operates in inverting mode using input AIN– as the signal input will restore the phase of the signal to its original orientation.

INPUT DRIVER CONFIGURATIONS

Transformer-Coupled Interface

If the application requires a signal conversion from a singleended source to drive the ADS5120 differentially, a RFtransformer might be a good solution. The selected transformer must have a center tap in order to apply the commonmode DC-voltage necessary to bias the converter inputs. AC-grounding the center tap will generate the differential signal swing across the secondary winding. Consider a stepup transformers to take advantage of signal amplification without the introduction of another noise source. Furthermore, the reduced signal swing from the source may lead to an improved distortion performance. The differential input configuration may provide a noticeable advantage of achieving good SFDR performance over a wide range of input frequencies. In this mode both inputs (AIN+ and AIN–) of the ADS5120 see matched impedances. Figure 2 shows the schematic for the suggested transformer coupled interface circuit. The component values of the R-C low-pass may be optimized depending on the desired roll-off frequency.

Single-Ended, AC-Coupled Driver

The circuit of Figure 3 shows an example for driving the inputs of the ADS5120 in a single-ended configuration. The signal is AC-coupled between the driver amplifier and the converter input (AIN+). This allows for setting the required common-mode voltages for the ADC and op amp separately. The single-supply op amp is biased at mid-supply by two resistors connected at its noninverting input. Connecting each input to the CML pin provides the required common-mode voltage for the inputs of the ADS5120. Here two resistors of equal value ensure that the inputs see closely matched source impedances. If the op amp features a disable function, it could be easily tied together with the power-down pin of the ADS5120 channel (STBY). In the circuit example depicted in Figure 3, the OPA355's EN-pin is

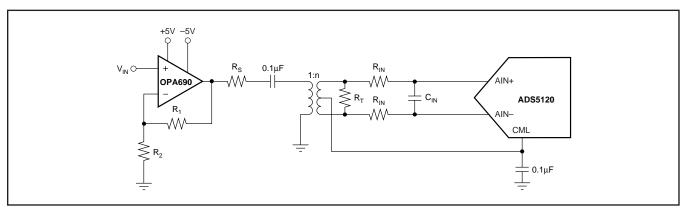


FIGURE 2. Converting a Single-Ended Input Signal into a Differential Signal Using a RF-Transformer.

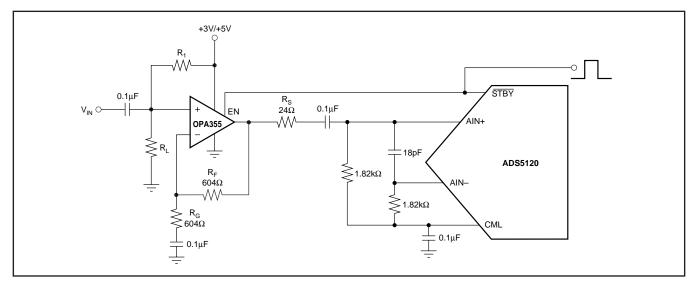


FIGURE 3. Single-Ended, AC-Coupled Driver Configuration for Single Supply.





directly connected to the STBY pin to allow for a power-down mode of the entire circuit. Other, suitable op amps for singlesupply driver applications include the OPA634, OPA635, or OPA690, for example.

DC-Coupled Interface with Differential Amplifier

Differential input/output amplifiers can simplify the driver circuit for applications requiring input DC-coupling. Flexible in their configurations, such amplifiers can be used for singleended to differential conversion, allow for signal amplification, and also filtering prior to the ADC. Figure 4 shows one possible circuit implementation using the THS4130 amplifier. Here, the amplifier operates with a gain of +2. The commonmode voltage available at the CML-pin can be conveniently connected to the amplifier's VOCM-pin to set the required input bias for the ADS5120.

REFERENCE OPERATION

For proper operation of the ADS5120 and its reference, an external $6.19 k \Omega$ resistor must be connected from the

IREFR-pin to analog ground, AGND (as shown in Figure 5). While a 1% resistor tolerance is adequate, deviating from this resistor value will cause altered and degraded performance.

To ensure proper operation with any reference configuration it is necessary to provide solid bypassing at all reference pins in order to keep the clock feed-through to a minimum. Figure 5 shows the recommended decoupling scheme. Good performance can be obtained using 0.1μ F low inductance ceramic capacitors. Adding tantalum capacitor (1μ F to 10μ F) may lead to a performance improvement, depending on the application. All bypassing capacitors should be located as close to their respective pins as possible.

INTERNAL REFERENCE

The internal reference circuit of the ADS5120 consists of a bandgap voltage reference, the drivers for the top- and bottom reference, and the resistive reference ladder. The corresponding reference pins are REFT, REFB, CML, IREFR, BG, and PDREF. In order to enable the internal reference,

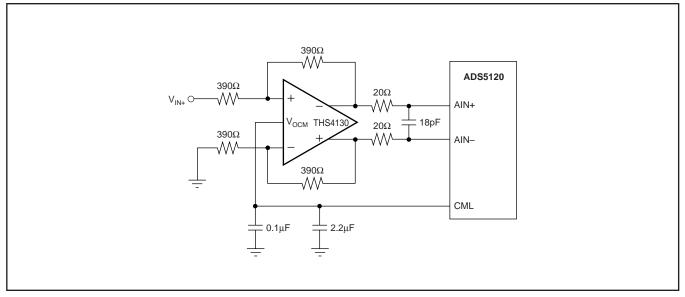


FIGURE 4. DC-Coupled Interface Using Differential I/O Amplifier THS4130.

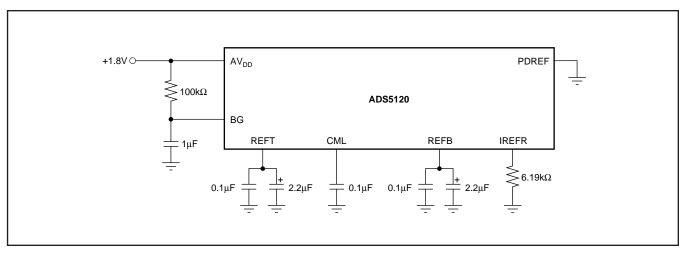


FIGURE 5. Internal Reference; Recommended Configuration and Bypassing.



pin PDREF must be at a logic LOW = 0 level. In addition, the bandgap pin BG must have a $100k\Omega$ pull-up resistor to AV_{DD}, and should be decoupled with a 1μ F capacitor. The reference circuit provides the reference voltages to each of the eight channels.

The reference buffers can be utilized to supply up to 1mA (sink and source) to an external circuitry. The common-mode level output pin, CML, represents the mid-point of the internal resistor ladder and is an un-buffered node. Loading of this pin should be avoided, as it will lead to degradation of the converter's linearity.

USING EXTERNAL REFERENCES

For even more design flexibility, the internal reference can be disabled and an external reference voltage used. The utilization of an external reference may be considered for applications, requiring higher accuracy or improved temperature performance. Especially in multi-channel applications, the use of a common external reference has the benefit of obtaining better matching of the full-scale range between converters.

Setting the ADS5120 for external reference mode requires taking the PDREF-pin HIGH. In addition, pins BG and REFT must be connected together (as shown in Figure 6). The common-mode voltage at the CML pin will be maintained at approximately the mid-point of the applied reference voltages, according to CML ≈ (VREFT - VREFB)/2. The internal buffer amplifiers for REFT and REFB are disabled when the ADS5120 operates in the external reference mode. The external reference circuit must be designed to drive the internal reference ladder (80Ω) located between the REFT and REFB pins. For example, setting REFT = +1.25V and REFB = +0.75V will require a current drive capability of at least $0.5V/80\Omega = 6.25$ mA. The external references can vary as long as the value of the external top reference (REFT_{EXT}) stays within the range of +1.15V to +1.35V, and the external bottom reference (REFB_{EXT}) stays within +0.65V to +0.85V (as shown in Figure 7).

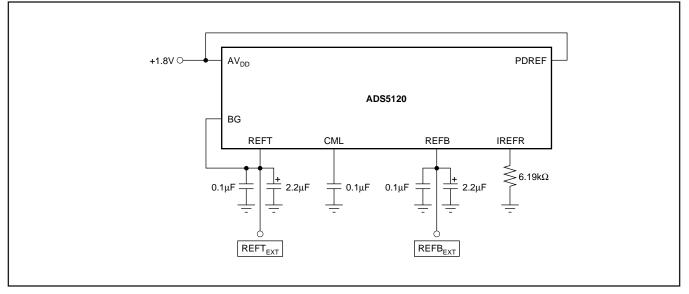


FIGURE 6. External Reference; Recommended Configuration and Bypassing.

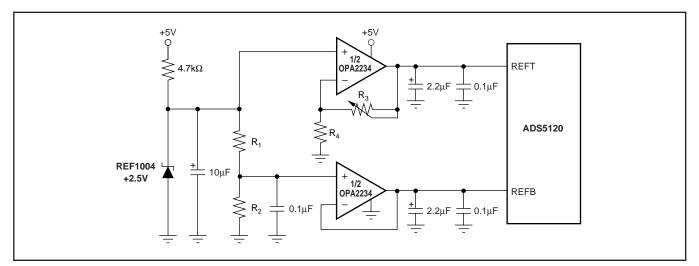


FIGURE 7. Circuit Example of an External Reference Circuit Using Single-Supply, Low Power, Dual Op Amp (OPA2234).





DIGITAL INPUTS AND OUTPUTS Clock Input

The clock input is designed to operate with +1.8V or +3.3V CMOS logic levels. The clock circuitry is internally connected to the DRV_{DD} supply. Therefore, the input High- and Low levels will vary depending on the applied DRV_{DD} supply, see 'Digital Characteristics'. Since both edges of the clock are used in this pipeline ADC, the ideal clock should be a square-wave logic signal with a 50% duty-cycle.

Since this condition cannot always easily be met, the ADS5120 features an internal clock conditioning circuitry that can be activated through the duty-cycle adjust pin (DCASEL).

The DCASEL-pin is a logic input, with its logic levels related to the DV_{DD} supply (+1.8V only):

- a) DCASEL = Low (GND); in this mode the clock conditioning circuitry is disabled. Use this setting if the applied clock signal is a square-wave clock with a duty cycle of 50%; or if the duty cycle stays within a range of 48% to 52%.
- b) DCASEL = High (DV_{DD}); in this mode the clock conditioning circuitry is enabled. Use this setting if the applied external clock signal is a square-wave clock that does not meet the criteria listed above, but has a duty cycle in the range of 30% to 70%.

MINIMUM SAMPLING RATE

The pipeline architecture of the ADS5120 uses a switched capacitor technique for the internal track-and-hold stages. With each clock cycle, charges representing the captured signal level are moved within the ADC pipeline core. The high sampling rate necessitates the use of very small capacitor values. In order to hold the droop errors LOW, the capacitors require a minimum 'refresh rate'. To maintain full accuracy of the acquired sample charge, the sampling clock of the ADS5120 should not be lower than the specified minimum of 1MSPS.

DATA OUTPUT FORMAT

The output data format of the ADS5120 is a positive Straight Offset Binary (SOB) code. Tables I and II show output coding of a single-ended and differential signal. For all data output channels, the MSBs are located at the D9x pins.

SINGLE-ENDED INPUT (AIN- = CML)	STRAIGHT OFFSET BINARY (SOB)
+FS-1LSB (AIN+ = CML + FSR/2)	11 1111 1111
+1/2 FS	11 0000 0000
Bipolar Zero (AIN+ = CML)	10 0000 0000
-1/2 FS	01 0000 0000
-FS (AIN+ = CML - FSR/2)	00 0000 0000

TABLE I. Coding Table for Single-Ended Input Configuration with Input AIN– Tied to the Common-Mode Voltage (CML).

DIFFERENTIAL INPUT	STRAIGHT OFFSET BINARY (SOB)
+FS – 1LSB (AIN+ = REFT, AIN– = REFB)	11 1111 1111
+1/2 FS	11 0000 0000
Bipolar Zero (AIN+ = AIN- = CML)	10 0000 0000
-1/2 FS	01 0000 0000
-FS (AIN+ = REFB, AIN- = REFT)	00 0000 0000

TABLE II. Coding Table for Differential Input Configuration and 1Vp-p Full-Scale Range.

DIGITAL OUTPUT LOADING

Minimizing the capacitive loading on the digital outputs is very important in achieving the best performance. The total load capacitance is typically made up of two sources: the next stage input capacitance and the parasitic/pc-board capacitance. It is recommended to keep the total capacitive loading on the data lines as low as possible (≤ 15 pF). Higher capacitive loading will cause larger dynamic currents as the digital outputs are changing states. High current surges may cause feedback into the analog portion of the ADS5120 and affect the performance. If necessary, external buffers or latches close to the converter's output pins may be used to minimize the capacitive loading. A suggested device is the SN74AVC16827 (20-bit buffer/driver), a member of the 'Advanced Very-Low Voltage CMOS' logic family (AVC). Using such a logic device can also provide the added benefit of isolating the ADS5120 from any digital noise activities on the bus coupling back high frequency noise. Some applications may also benefit from the use of series resistors ($\leq 100\Omega$) in the data lines. This will provide a current limit and reduce any existing over- or undershoot.

OUTPUT ENABLE

The ADS5120 provides one output enable pin (\overline{OE}) that controls the digital outputs of all channels simultaneously. A low (L = 0) level on the \overline{OE} pin will have all channels active and the converter in normal operation. Taking the \overline{OE} pin high (H = 1) will disable or tri-state the outputs of all channels. Note that the \overline{OE} pin has no internal pull-up resistor and therefore requires a defined potential to be applied. The timing relations between \overline{OE} and the output bus enable/ disable times are shown in the Timing Diagram.

POWER-DOWN (STANDBY)

The ADS5120 is equipped with a power-down function for each of the eight channels. Labeled as \overline{STBY} pins, the normal operational mode is when this pin is connected to logic high (H = 1). The selected ADC channel will be in a power-down mode if the corresponding \overline{STBY} pin is connected to logic LOW (L = 0). The logic levels for the \overline{STBY} pins are dependent on the DRV_{DD} supply. The power-down function controls internal biasing nodes, and as a consequence, any data present in the pipeline of the converter will become invalid. This is independent of whether the clock remains applied during power-down, or not. Following a



power-up, new, valid data will become available after a minimum of seven clock cycles. As a note, the operation of the $\overline{\text{STBY}}$ pins is not intended for the use of dynamically multiplexing between the eight channels of the ADS5120.

DIGITAL OUTPUT DRIVER SUPPLY, DRV_{DD}

The ADS5120 uses a dedicated supply connection for the output logic drivers, DRV_{DD} , along with its digital driver ground connections, labeled DRGND.

Setting the voltage at DRV_{DD} to either +3.3V or +1.8V the output logic levels are set accordingly, allowing the ADS5120 to directly interface to a selected logic family. The output stages are designed to supply sufficient current to drive a variety of logic families. However, it is recommended to use the ADS5120 with a +1.8V driver supply. This will lower the power dissipation in the output stages due to the lower output swing and reduce current glitches on the supply lines, which otherwise may affect the AC-performance of the converter. In some applications it might be advantageous to decouple the DRV_{DD} supply with additional capacitors or a pi-filter.

GROUNDING AND DECOUPLING

Proper grounding and bypassing, short lead length, and the use of ground planes are particularly important for high frequency designs. Multilayer pc-boards are recommended for best performance since they offer distinct advantages like minimizing ground impedance, separation of signal layers by ground layers, etc. The ADS5120 should be treated as an analog component. Whenever possible, the supply pins should be powered by the analog supply. This will ensure the most consistent results, since digital supply lines often carry high levels of noise which otherwise would be coupled into the converter and degrade the achievable performance. The ground pins should directly connect to an analog ground plane covering the pc-board area under the converter. While designing the layout it is important to keep the analog signal traces separated from any digital line to prevent noise coupling onto the analog signal path. Because of the its high sampling rate the ADS5120 generates high frequency current transients and noise (clock feedthrough) that are fed back into the supply and reference lines. This requires that all supply and reference pins are sufficiently bypassed. In most cases 0.1µF ceramic chip capacitors at each pin are adequate to keep the impedance low over a wide frequency range. Their effectiveness largely depends on the proximity to the individual supply pin. Therefore they should be located as close to the supply pins as possible. In addition, a larger bipolar capacitor (1µF to 22µF) should be placed on the pcboard in proximity of the converter circuit.

LAYOUT OF PCB WITH MICROSTAR BGA™ PACKAGE

The ADS5120 is housed in a polymide film-based chipscale package (CSP). Like most CSPs, solder alloy balls are used as the interconnect between the package substrate and the board on which the package is soldered. For detailed information regarding these packages, please refer to literature number SSYZ015B, MicroStar BGA Packaging Reference Guide, which addresses the specific considerations required when integrating a MicroStar BGA package into the PCB design. This document can be found at:

http://www-s.ti.com/sc/psheets/ssyz015b/ssyz015b.pdf



TERMINOLOGY

ANALOG BANDWIDTH

The analog input frequency at which the spectral power of the fundamental frequency (as determined by the FFT analysis) is reduced by 3dB.

APERTURE DELAY

The delay between the 50% point of the rising edge of the Clock and the instant at which the analog input is sampled.

APERTURE UNCERTAINTY (JITTER)

The sample-to-sample variation in aperture delay.

EFFECTIVE NUMBER OF BITS (ENOB)

The ENOB is calculated from the measured SINAD based on the equation:

$$\mathsf{ENOB} = \left(\frac{\mathsf{SINAD} - 1.76\mathsf{dB}}{6.02}\right)$$

GAIN ERROR

Gain Error is the deviation of the actual difference between first and last code transitions and the ideal difference between first and last code transitions.

GAIN MATCHING

Variation in Gain Error between adjacent channels.

HARMONIC DISTORTION, SECOND

The ratio of the rms signal amplitude to the rms value of the second harmonic component, reported in dBc.

HARMONIC DISTORTION, THIRD

The ratio of the rms signal amplitude to the rms value of the third harmonic component, reported in dBc.

INTERMODULATION DISTORTION (IMD)

The two-tone IMD is the ratio expressed in decibels of either input tone to the worst third-order (or higher) Intermodulation products. The individual input tone levels are at -6.5dB full-scale, and their envelope is at -0.5dB full-scale.

OFFSET ERROR (ZERO SCALE ERROR)

The first transition should occur for an analog value 1/2 LSB above –full-scale. Offset error is defined as the deviation of the actual transition from that point.

OFFSET MATCHING

The change in offset error between adjacent channels.

POWER SUPPLY REJECTION RATIO (PSRR)

The ratio of a change in input offset voltage to a change in power supply voltage.

SIGNAL-TO-NOISE AND DISTORTION (SINAD)

The ratio of the rms signal amplitude (set 0.5dB below fullscale) to the rms value of the sum all other spectral components, including harmonics but excluding DC.

SIGNAL-TO-NOISE RATIO (WITHOUT HARMONICS)

The ratio of the rms signal amplitude (set 0.5dB below fullscale) to the rms value of the sum of all other spectral components, excluding the first five harmonics and DC.

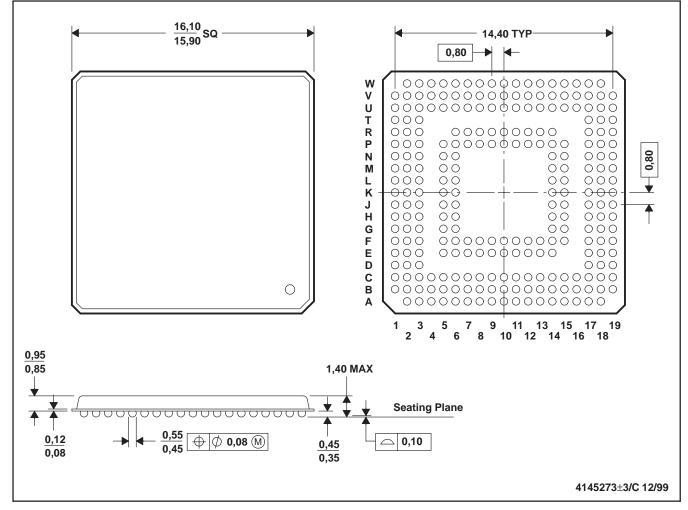
SPURIOUS-FREE DYNAMIC RANGE (SFDR)

The ratio of the rms signal amplitude to the rms value of the peak spurious spectral component. The peak spurious component may or may not be a harmonic. May be reported in dBc (i.e., degrades as signal level is lowered), or dBFS (always related back to converter full-scale).



GHK (S-PBGA-N257)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. MicroStar BGA[™] configuration



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third–party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Mailing Address:

Texas Instruments Post Office Box 655303 Dallas, Texas 75265

Copyright © 2002, Texas Instruments Incorporated